PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

July 28, 2010

Applicants: Toshihiro TAI et al

For: PLATED RESIN MOLDED ARTICLES

Serial No.: 10/586 378   Group: 1787

Confirmation No.: 2951

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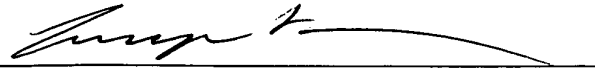Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

LETTER TO EXAMINER

Sir:

        This Request for Continued Examination (RCE) is being
filed in order to have the Amendment After Final Rejection
dated June 25, 2010 entered into the record of the present
application. As stated in the previous Response, the instant
invention provides a plated resin molded article which
exhibits a high adhesion strength between a thermoplastic
resin molded article and a metal plating layer and also
imparts a beautiful aesthetic appearance to the plated resin
molded article. The articles prepared by the present
invention are provided by a treatment that does not need the
use of a heavy metal-containing acid and therefore avoids
problems with respect to environmental hazards that occur
through the use of a heavy metal etching treatment. The five
components used in providing the thermoplastic resin molded
article of the present invention have a synergistic effect in
giving an improved adherence strength to a metal plating

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layer. The prior art cited by the Examiner does not disclose the presently claimed invention. Favorable consideration is respectfully solicited.

Respectfully submitted,

Terryence F. Chapman

TFC/smd

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Encl: None

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